Docket No. _JCLA 5085



Form 1595 1-31-92

RECORDATION

PATENTS ONLY

101149533

U.S. Department of Commerce

Patent and Trademark Office

To the Honorable Assistant Commissioner for Patents: Please record the attached original documents or copy thereof. Name of conveying party(ies): 2. Name/address of receiving Party(ies): Chien-Jung Wang Worldwide Semiconductor Ling-Sung Wang Manufacturing Corp. ☐ Merger ☐ Security Agreement ☐ Other No. 25, Li-Hsin Rd., Science-Based ☐ Change of Name ☐ Reassignment Industrial Park, Hsinchu, Taiwan, 4. Date(s) of execution: August 25, 1999 Add'1 names of receiving parties Attached? Yes No Application number(s) or patent number(s): 091 393983 If this documents is being filed together with a new application, the execution date of the application is _August 25, 1999 A. Patent Application No. (s) Patent No. (s) Additional numbers attached? ☐ Yes ☒ No 7. Total No. of applications and patents Name and address of party to whom involved: correspondence concerning document should be mailed: ONE(1)Total fee (37 CFR §3.41): \$40.00 J.C. Patents, Inc. Enclosed 1340 Reynolds Ave., Suite 114 Irvine, CA 92614 Charge to Acct. No. (949) 660-0761 Total number of pages, including cover sheet, attachments and document 3. DO NOT USE THIS SPACE 10. Statement and Signature: To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Registration No. 43, 330

00000025 09393983 09/20/1999 MTHAI1

01 FC:581

40.00 OP

Jiawei Huang Name of Person Signing

> **PATENT** REEL: 010236 FRAME: 0070

ASSIGNMENT

WHEREAS,

1. Chien-Jung Wang

2. Ling-Sung Wang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: A FABRICATION METHOD OF A DEVICE ISOLATION STRUCTURE

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Worldwide Semiconductor Manufacturing Corp.

of No. 25, Li-Hsin Rd., Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof,

-1-

ASSIGNMENT CONTINUED

and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Cluben - Teny henry

8/25 99

Signature:

Sole or First Joint Inventor: Chien-Jung Wang

Signature:

Second Joint Inventor: Ling-Sung Wang

RECORDED: 09/10/1999

Aug. 25, 199

Date: